

Supporting Information

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Integrated Gradient Cu Current Collector Enables Bottom-Up Li Growth for Li Metal Anodes: Role of Interfacial Structure

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Figure S1. The preparation and characteristics of (a-c) S-Cu(OH)₂@Cu, (d-f) M-Cu(OH)₂@Cu and (g-i) D-Cu(OH)₂@Cu: (a, d, g) curves of galvanostatic anodization, (b, e, h) SEM images and (c, f, i) XRD patterns.



Figure S2. Surface SEM images of (a, b) S-CuO@Cu and (c, d) D-CuO@Cu nanowire arrays.



Figure S3. Cross-section SEM images of (a) S-CuO@Cu and (b) D-CuO@Cu nanowire arrays.



Figure S4. Digital photographs of resistance measures with digital multimeter for (a) bare Cu, (b) S-CuO@Cu, (c) M-CuO@Cu, (d) D-CuO@Cu nanowire arrays. All samples were punched into a circle with a diameter of 12 mm and the two test probes were maintained at a fixed length of 10 mm.



Figure S5. Cyclic voltammetry tests of half cells based on the (a) S-CuO@Cu, (b) M-CuO@Cu, (c) D-CuO@Cu electrodes at programmed scan rates. (d) The estimation of C_{dl} by plotting the current density variation against scan rate.



Figure S6. Digital photographs of molten Li infusion. All procedures were conducted on a hotplate with 300 °C in an argon-filled glove box.



Figure S7. Contact angle tests of (a) bare Cu, (b) S-CuO@Cu, (c) M-CuO@Cu and (d) D-CuO@Cu nanowire arrays with the electrolyte solution.



Figure S8. Comparison of CE for different electrodes at the (a) 3 mA cm^{-2} for 1 mAh cm^{-2} and (b) 1 mA cm^{-2} for 3 mAh cm^{-2} .



Figure S9. Cycling performance of symmetric cells based on different electrodes at 2 mA cm⁻² for 1 mAh cm⁻².



Figure S10. Cross-section SEM images of (a) S-CuO@Cu-Li, (b) M-CuO@Cu-Li, and (c) D-CuO@Cu-Li based on symmetric cells after 200 cycles at 1 mA cm⁻² and 1 mAh cm⁻².



Figure S11. The equivalent circuit used for EIS analyses.



Figure S12. Change in R_{ct} of different electrodes before cycling, and after 50th and 100th cycles.



Figure S13. (a, b) SEM images of M-CuO@Cu after 0.25 mAh cm⁻² Li plating at 0.25 mA cm⁻².



Figure S14. SEM images of (a) bare Cu, (b) S-CuO@Cu, (c) M-CuO@Cu, (d) D-CuO@Cu after 3 mAh cm⁻² Li plating and then fully stripping at 0.25 mA cm⁻².



Figure S15. SEM images of the (a) pristine and (b-d) cycled LFP cathodes after 150 cycles at 1 C based on (b) LFP || S-CuO@Cu-Li, (c) LFP || M-CuO@Cu-Li, and (d) LFP || D-CuO@Cu-Li full cells.

Table S1. Comparison of cycling performance of symmetric cells based on functionalized Cu

 current collectors.

Current Collector	Current density (mA cm ⁻²)	Areal capacity (mAh cm ⁻²)	Cycling time (h)	Overpotential (mV)	Ref.
3D porous Cu current collector	1	1	400	~20	[1]
3D porous Cu current collector	1	1	800 535	~11 ~15	[2]
3D porous Cu current collector	0.2	1	1000	~26	[3]
3D Cu current collector with submicron skeleton	0.2	1	600	~50	[4]
3D duplex Cu current collector	0.5	1	960	~13	[5]
	1	1	880	~17	
Cu-CuO-Ni current collector	0.5	0.5	580	~12	[6]
Cu foil-supported Cu ₃ P	1	1	1000	~30	[7]
nanowires	2	2	450	~30	[/]
MOF-derived carbon framework/Ag deposited Cu current collector	0.4	0.4	500	~20	[8]
N-doped CuO nanosheet- decorated Cu current collector	1	1	600	23.1	[9]
Vertically aligned carbon nanofiber array grown on Cu current collector	1	2	500	~35	[10]
M-CuO@Cu current	1	1	1200	10	This
collector	2	1	500	24	work

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